N-Channel 100 V (D-S) MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	R _{DS(on)} (mΩ)(Typ.)	I _D (A) ^a	Q _g (Typ.)		
100	125 at V _{GS} = 10 V	2	18.5 nC		
100	130 at V_{GS} = 4.5 V	3			

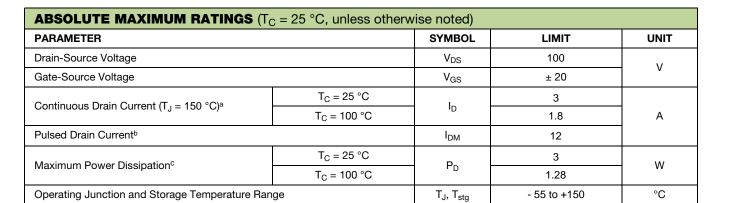
FEATURES

- DT-Trench Power MOSFET
- 100 % R_g and UIS Tested
- · Optimized for fast-switching applications

APPLICATIONS

- Synchronous Rectification
- Isolated DC/DC Converters in Telecom and Industrial

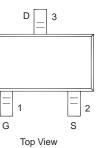
N-Channel MOSFET



THERMAL RESISTANCE RATINGS						
PARAMETER	SYMBOL	MAX	UNIT			
Junction-to-Ambient (PCB Mount) ^d	R _{thJA}	120 °C				
Junction-to-Case (Drain)	R _{thJC}	39	- °C/W			

Notes

- a. Calculated continuous current based on maximum allowablejunction temperature.
- b. Repetitive rating; pulse width limited by max. junction temperature.
- c. Pd is based on max. junction temperature, using junction-case thermal resistance.
- d. The value of $R_{\theta JA}$ is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with Ta=25 °C.



(SOT-23-3L)





DTS1004-G

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Parameter	Symbol	Test Conditions		Тур.	Max.	Unit	
Static		•					
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0, I_D = 250 \ \mu A$	100			V	
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \mu A$	1		3	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 100 V, V _{GS} = 0 V			1		
Zero Gale voltage Drain Guirent		V _{DS} = 80 V, V _{GS} = 0 V, T _J = 55 °C			10	μA	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \geq 5$ V, V_{GS} = 4.5 V	3			Α	
Drain-Source On-State Resistance ^a	Р	V _{GS} = 10 V, I _D = 2 A		125	150		
Drain-Source On-State Resistance-	R _{DS(on)}	V _{GS} = 4.5 V, I _D = 2 A		130	160	mΩ	
Forward Transconductance ^a	9 _{fs}	$V_{DS} = 5 V I_D = 2 A$		5		S	
Dynamic ^b	l.						
Input Capacitance	C _{iss}			1040		pF	
Output Capacitance	C _{oss}	V_{DS} = 50 V, V_{GS} = 0 V, f = 1 MHz		23			
Reverse Transfer Capacitance	C _{rss}			17			
Total Gate Charge	Qg			18.5		nC	
Gate-Source Charge	Q _{gs}	$V_{DS} = 50 \text{ V}, \text{ V}_{GS} = 10 \text{ V}, \text{ I}_{D} = 2 \text{ A}$		2			
Gate-Drain Charge	Q _{gd}			2.5			
Gate Resistance	R _g	f = 1 MHz	f = 1 MHz			Ω	
Turn-On Delay Time	t _{d(on)}			8			
Rise Time	t _r	$V_{DD} = 50 \text{ V}, \text{ R}_{L} = 25 \Omega$		6		ns	
Turn-Off DelayTime	t _{d(off)}	$I_D \cong$ 2 A, V_{GEN} = 10 V, R $_g$ = 1 Ω		23			
Fall Time	t _f			5			
Drain-Source Body Diode Characterist	ics	•		•		1	
Continous Source-Drain Diode Current	۱ _S	T _C = 25 °C			3	•	
Pulse Diode Forward Current	I _{SM}				12	A	
Body Diode Voltage	V _{SD}	I _S = 1 A			1.2	V	
Body Diode Reverse Recovery Time	t _{rr}	L = 2.0 d/dt = 100.0/up T = 25.00		15		ns	
Body Diode Reverse Recovery Charge	Reverse Recovery Charge Q_{rr} $I_F = 2 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 \text{ °C}$			30		nC	

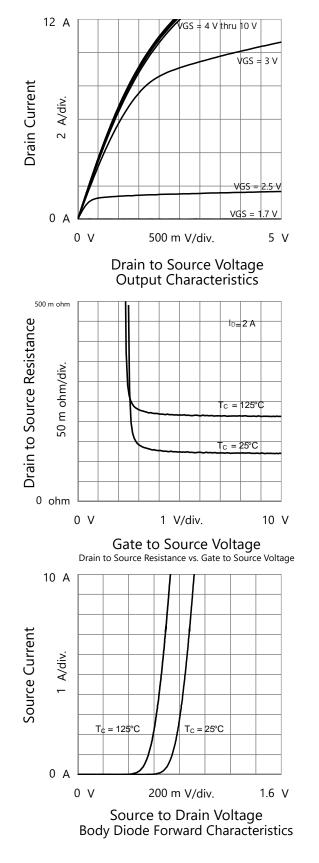
Notes:

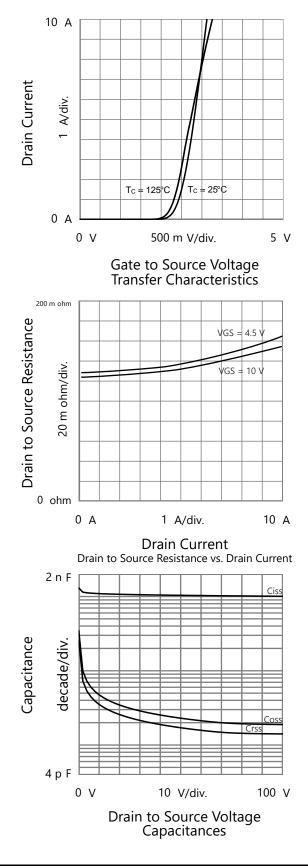
a. Pulse test; pulse width \leq 300 μs , duty cycle \leq 2 %. b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



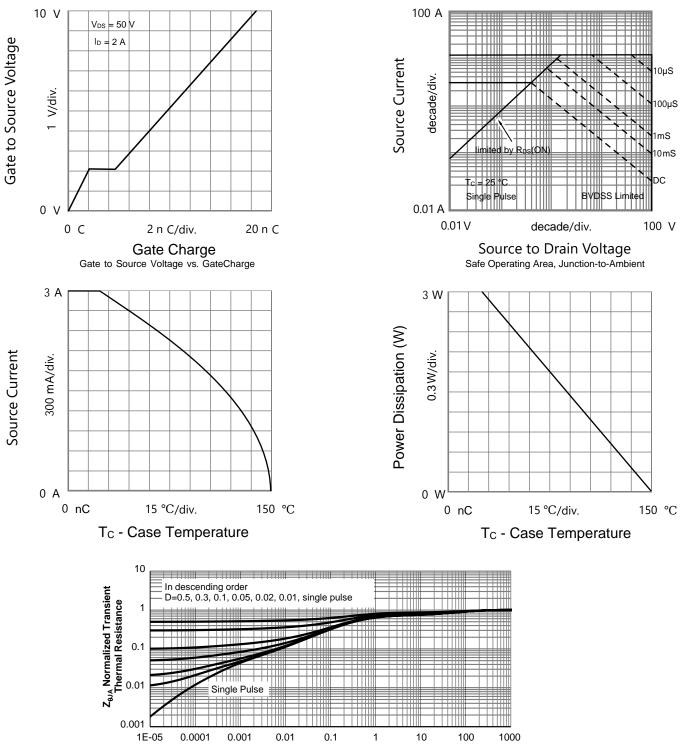
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)





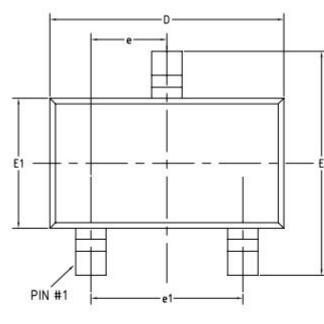


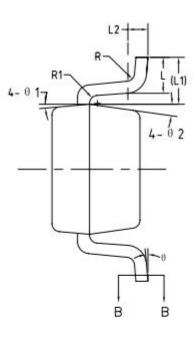
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

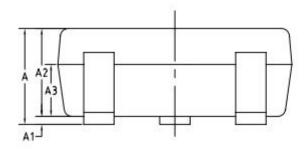


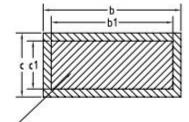
Pulse Width (s) Normalized Maximum Transient Thermal Impedance

SOT-23-3L PACKAGE OUTLINE









BASE METAL SECTION B-B

COMMON DIMENSIONS (UNITS OF MEASURE=MILLIMETER)

SYMBOL	MIN	TYP	MAX
Α	-	-	1.50
A1	0.00	-	0.18
A2	0.85	1.10	1.35
A3	0.58	0.65	0.72
b	0.23	-	0.53
b1	0.20	0.40	0.50
с	0.09	-	0.22
c1	0.08	0.13	0.21
D	2.78	2.95	3.10
E	2.58	2.80	3.03
E1	1.55	1.65	1.78
е	0.83	0.95	1.07
e1	1.78	1.90	2.02
L	0.28	0.45	0.62
L1	0.59REF		
L2	0.25BSC		
R	0.04	-	-
R1	0.04	-	0.21
θ	0°	-	8°
θ1	8°	10°	12°
θ2	8°	10°	12°



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